

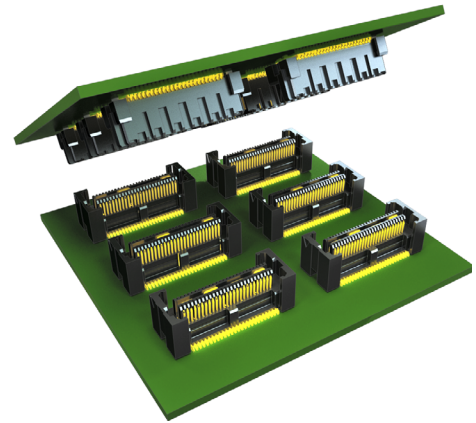
Multiple Connector Applications

Application Overview

The majority of Samtec's vertical board-to-board connectors are capable of being used in applications where multiple connectors are placed on a single board and mated simultaneously. When using multiple connectors per board, there is a higher potential for misalignment; however, following the recommendations in this document should prevent this issue.

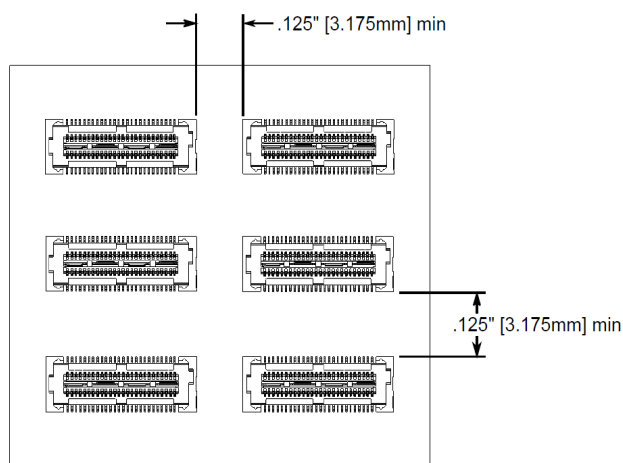
When using multiple connectors per board, Samtec recommends:

- Closely following the Samtec recommended footprint and stencil designs
- Ensuring a good solder print
- Machine placing the components
- Holding the drill diameter tolerances for the alignment pin holes to +/- .002" [.050mm]



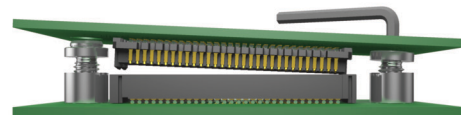
Each connector series has a unique maximum recommended misalignment in the X and Y directions to ensure a good mate. Some of Samtec's finer pitch (i.e. .4mm, .5mm) products have very limited allowable misalignment. For the maximum X and Y misalignment of a specific series, please reference its product specification which is available on the Samtec website.

For rework considerations, Samtec recommends a minimum spacing of .125" between adjacent components.



Note:

To aid in the unmating of boards which have multiple connectors or high unmating forces, or which require parallel unmating, Samtec offers the Jackscrew Standoffs (JSO).



www.samtec.com/products/jso

For more information, please contact the Samtec Interconnect Processing Group at ipg@samtec.com.

These guidelines should not be considered design requirements for all applications. Samtec recommends testing interconnects on your boards in your process to guarantee optimum results.